

ECOREL™ SINTEC

Next generation sintering solutions

APPLICATION FIELD

Sintering solutions are used as an alternative to solder paste in applications where high thermal and electrical conductivity, reliability, and mechanical strength are critical.

Some key areas where sintering is preferred include lead free die-attach, large area module attach, E-Vehicle, Energy conversion of Renewable energies, Optoelectronics and RF power devices.

Especially with the latest SiC and GaN developments operating at much higher power, using sintering interconnections with higher thermal and excellent electrical conductivity is crucial.

ADDITIONAL ADVANTAGES

- Processing with established equipment
- Highly reproducible and reliable
- Low electrical resistivity (3 $\mu\Omega$)
- No CMR containing substances, no halogen and no nanoparticle
- RoHS compliant
- Ten-fold improvement of E-module life-time
- Worldwide product availability & technical support

KEY FEATURES

1 High Thermal conductivity

ECOREL™ SINTEC sintering solutions achieve thermal conductivity values exceeding 300 W/mK, providing exceptional heat dissipation and making them an ideal choice for high-power applications.

2 High shear strength

With a shear strength exceeding 50 MPa, robust interconnects are formed, enabling assemblies to easily withstand Thermal Cycling Testing (TCT) from -55°C to +125°C for over 1000 cycles.

3 Room temperature storage

Most sintering pastes require refrigerated or frozen storage, but our sintering solutions can be stored at room temperature, making them much easier to handle, while still providing a 6 months shelf life.

GET IN TOUCH

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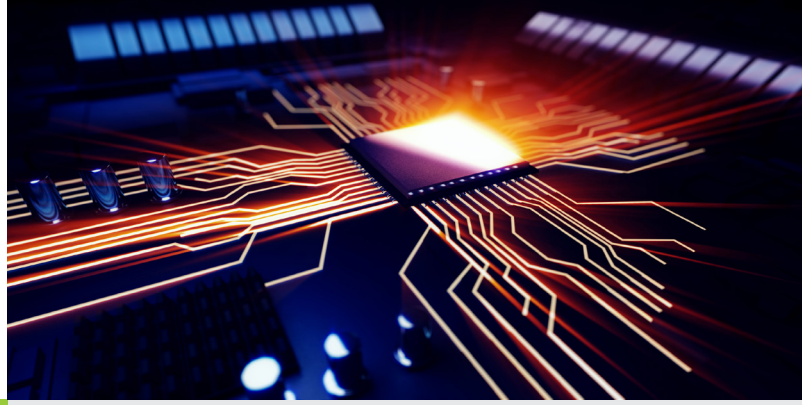
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The future of electronic assembly,
overcoming today's limits



ALL-IN-ONE SINTERING PROCESS

Die sintering & Substrate sintering
in one step

The All-in-One sintering process has the potential to reduce the total cost of ownership for such applications dramatically. Ideally, an usually two-step process, die sintering and substrate sintering, can become a one step process: saving energy, consumables, and time by 50%.

ECOREL™ SINTEC AP90 shows a great flexibility from small to large surface areas but also for material stacks which are prone to warpage during sintering and stress test.

ECOREL™ SINTEC PRODUCT RANGE

PRESSURE

PRINTING

ECOREL™ SINTEC AP90

- Optimal wetting and bonding
- High shear strength
- High conductivity

LARGE AREA DISPENSING

ECOREL™ SINTEC AP90D

- Compatible with flat-bed-dispensing
- Designed for substrate attach
- Low pressure sintering
- High flexibility for surface finishing

PRESSURELESS

PRINTING & DISPENSING

ECOREL™ SINTEC XP95

- Optimal wetting and bonding
- High shear strength
- High conductivity
- High flexibility for surface finishing

BASED ON **ngn-join** TECHNOLOGIES

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